



AUTOMATED CHEMICAL SOLUTIONS

Chemicals and Controllers for PWB Fabrication

Product Overview

μETCH EM-2110

Copper Microetch

Product Description

EM-2110 is a concentrated microetch additive designed to improve the performance and stability of generic hydrogen peroxide/sulfuric acid microetches. EM-2110's hydrogen peroxide stabilizers virtually eliminate destabilization losses. Etch accelerators and modifiers increase etch rate and improve surface topography. The result is a superior surface and improved performance for all processes requiring a microetch at remarkably low operating costs.

FEATURES

💡 Completely stabilizes hydrogen peroxide in the presence of metal ions even at elevated temperatures

💡 Rate enhancing additives

💡 Etch modifiers

BENEFITS

💰 Reduces operating cost through decreased consumption

🚀 Increases etch rate without increasing consumption

👉 Improves surface topography for increased coverage and adhesion in subsequent processes

Physical Properties

Specific gravity: 1.09
pH: 6-8
Appearance: clear, water white to amber liquid
Freezing point: <40 °F

Operating Parameters

Copper loading: 3 – 7 oz/gal (22.5 – 52.5 g/L)
Hydrogen peroxide concentration: 3% – 6% (as 50% hydrogen peroxide)
4.3% - 8.6% (as 35% hydrogen peroxide)
Sulfuric acid concentration: 5% – 10%
Temperature: 80 °F – 100 °F

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

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